

Electronic Patent Application Fee Transmittal**Application Number:**

10581395

Filing Date:

14-Aug-2008

Title of Invention:

Chip Scale Package and Method of Assembling the Same

First Named Inventor/Applicant Name:

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Filer:

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Attorney Docket Number:

Q78657

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees**Description****Fee Code****Quantity****Amount****Sub-Total in
USD(\$)****Basic Filing:****Pages:****Claims:****Miscellaneous-Filing:****Petition:****Patent-Appeals-and-Interference:**

Notice of appeal

1401

1

620

620

Post-Allowance-and-Post-Issuance:**Extension-of-Time:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$130 paid	1253	1	1140	1140
Miscellaneous:				
Total in USD (\$)				1760